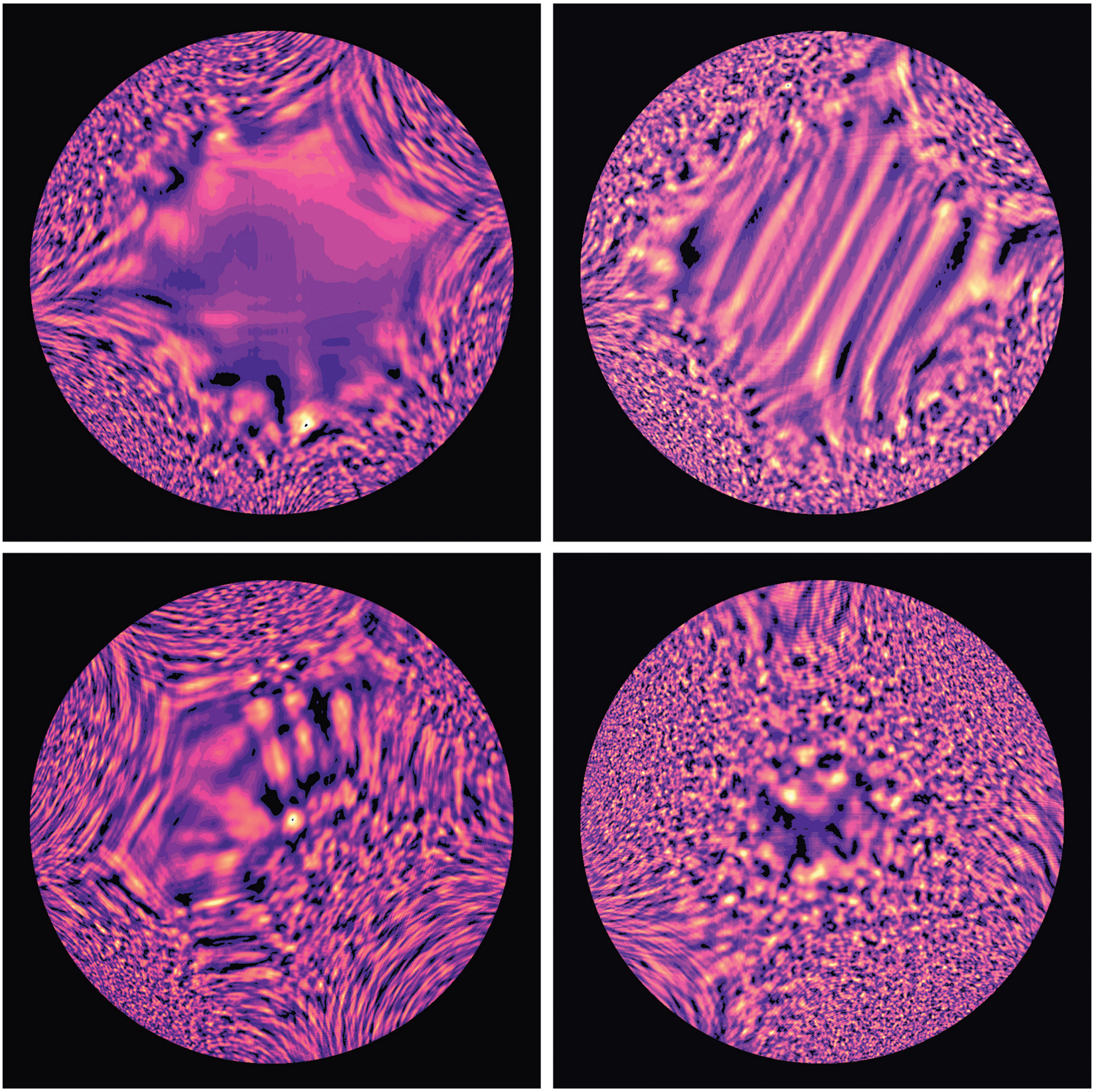
Volume **27** Number **3** 2019 **May**

Microscopy TODAY



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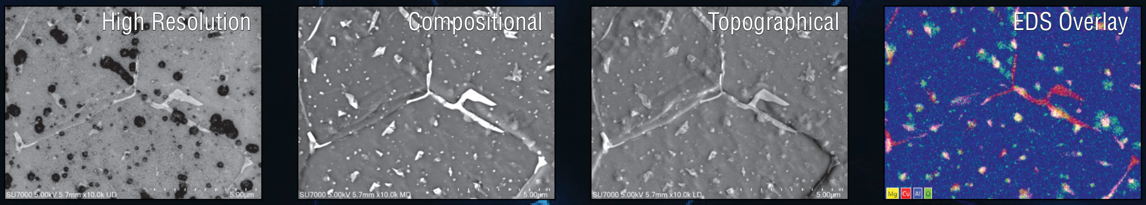

Sample: Heat-treated aluminum alloy

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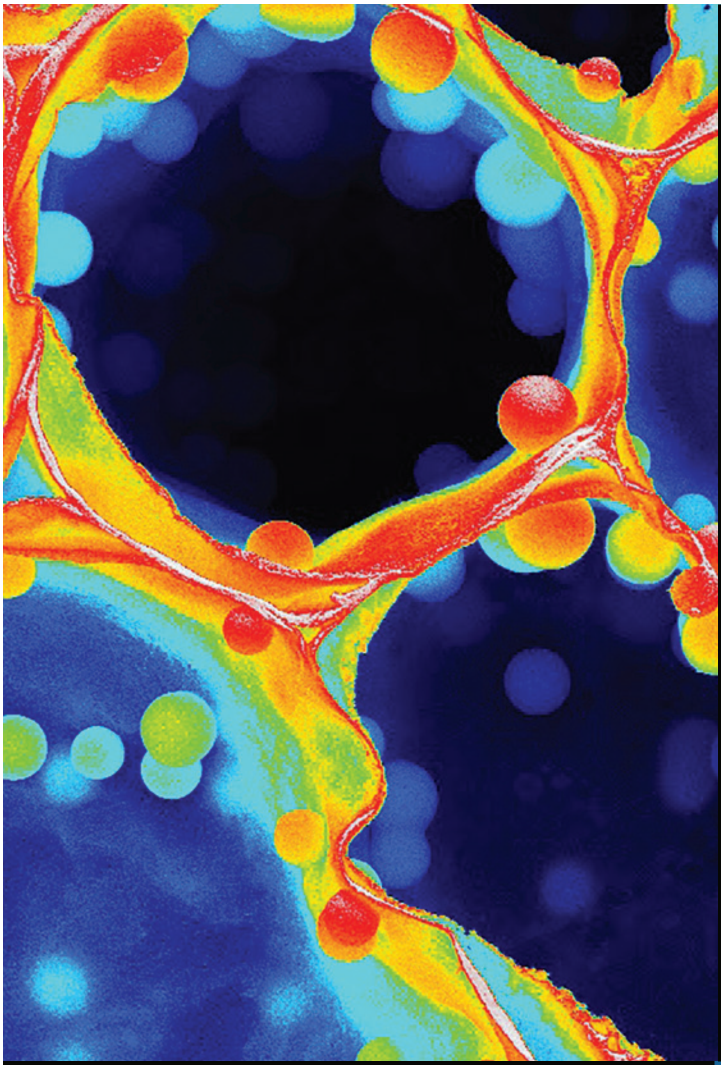

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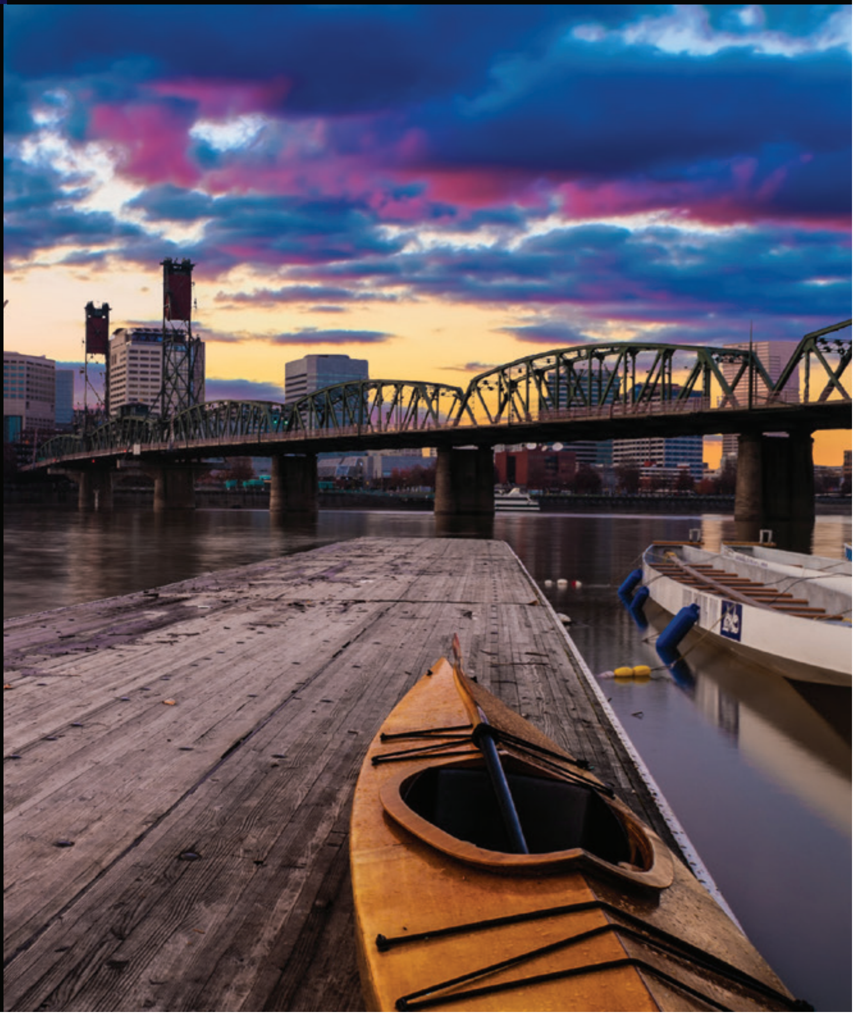

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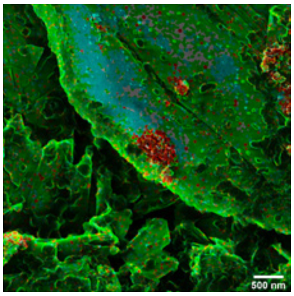

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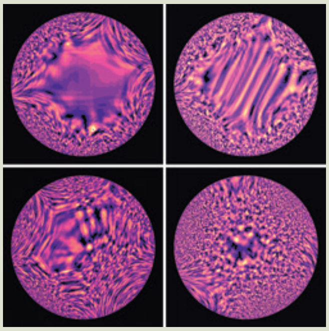

Simulated electron Ronchigrams for an aberration-corrected STEM. Clockwise from upper left: well-aligned STEM, two-fold astigmatism, three-fold astigmatism, and axial coma.

See article by Schnitzer et al.

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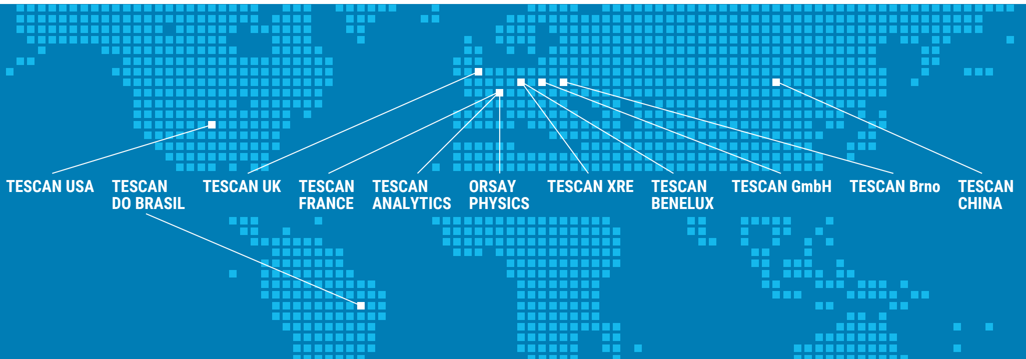
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